## **AMENDMENTS TO THE CLAIMS**

- 1. (Currently Amended) A liquid epoxy resin composition comprising:
- (A) a liquid epoxy resin consisting of a bisphenol type epoxy resin;
- (B) an aromatic amine curing agent; and
- (C) an inorganic filler in an amount of 100 to 600 parts by weight per 100 parts by weight of the epoxy resin, wherein

the aromatic amine curing agent (B) comprises at least 5% by weight based on the entire curing agent of at least one aromatic amine compound having a purity of at least 99% selected from compounds having the following general formulae (1) to (3):

$$R^1$$
 $R^3$ 
 $R^2$ 
 $R^4$ 
 $R^3$ 
 $R^4$ 
 $R^3$ 
 $R^4$ 

wherein each of R<sup>1</sup> to R<sup>4</sup> is hydrogen or a monovalent hydrocarbon group having 1 to 6 carbon atoms,

the liquid epoxy resin (A) and the aromatic amine curing agent (B) are present in a molar ratio (A)/(B) from 0.7/1 to less than 0.9/1 0.85/1, and

After Final Office Action of February 7, 2006

the composition has a toughness  $K_{1c}$  of at least 3.5, and is substantially free of an alkoxybearing silane coupling agent except that an alkoxybearing silane coupling agent is used for the surface treatment of the inorganic filler.

## 2-6. (Cancelled)

- 7. (Previously Presented) The composition of claim 1, wherein the composition has a toughness  $K_{1c}$  of at least 4.0.
- 8. (Previously Presented) The composition of claim 1, wherein the inorganic filler is spherical silica.

3

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